



Material Content Data Sheet



Sales Product Name	BFR 750L3RH E6327			Issued		29. August 2013		
MA#	MA000365021							
Package	PG-TSLP-3-9			Weight*		0.50 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.14		1382	
	noble metal	gold	7440-57-5	0.003	0.54		5359	
	inorganic material	silicon	7440-21-3	0.020	3.97	4.65	39710	46451
leadframe	non noble metal	nickel	7440-02-0	0.131	26.12	26.12	261200	261200
wire	noble metal	gold	7440-57-5	0.009	1.73	1.73	17277	17277
encapsulation	organic material	carbon black	1333-86-4	0.003	0.62		6195	
	plastics	epoxy resin	-	0.042	8.36		83627	
	inorganic material	silicondioxide	60676-86-0	0.266	52.96	61.94	529640	619462
leadfinish	noble metal	gold	7440-57-5	0.011	2.11	2.11	21121	21121
plating	noble metal	silver	7440-22-4	0.017	3.45	3.45	34489	34489
*deviation	< 10%	Sum in total:				100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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